

Application Specific Discretes $A.S.D.^{TM}$

EMI FILTER INCLUDING ESD PROTECTION

MAIN APPLICATIONS

Where EMI filtering in ESD sensitive equipment is required :

The EMIF01-10005W5 is a highly integrated array

designed to suppress EMI / RFI noise in all systems

Additionally, this filter includes an ESD protection circuitry

which prevents the protected device from destruction when

Cost-effectiveness compared to discrete solution

High flexibility in the design of high density boards
Very low PCB space consuming : 4.2 mm² typically
High reliability offered by monolithic integration

COMPLIES WITH THE FOLLOWING STANDARD:

(air discharge)

(contact discharge)

15kV

8 kV

subjected to electromagnetic interferences.

subjected to ESD surges up to 15 kV.

EMI bi-directional low-pass filterHigh efficiency in ESD suppression.

- Computers and printers
- Communication systems
- Mobile phones
- MCU Boards

DESCRIPTION

BENEFITS

IEC 1000-4-2



FUNCTIONAL DIAGRAM



Filtering response



ESD response to IEC1000-4-2 (16 kV air discharge)

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Symbol	Parameter and test conditions	Value	Unit
Vpp	ESD discharge IEC1000-4-2, air discharge ESD discharge IEC1000-4-2, contact discharge	16 9	kV
Tj	Junction temperature	150	°C
T _{op}	Operating temperature range	-40 to + 85	°C
T _{stg}	Storage temperature range	-55 to +150	°C
TL	Lead solder temperature (10 second duration)	260	°C

ABSOLUTE MAXIMUM RATINGS (Tamb = 25 °C)

ELECTRICAL CHARACTERISTICS (T_{amb} = 25 °C)

Symbol	Parameter
V _{BR}	Breakdown voltage
I _{RM}	Leakage current @ V _{RM}
V _{RM}	Stand-off voltage
V _{CL}	Clamping voltage
Rd	Dynamic impedance
IPP	Peak pulse current
R _{I/O}	Series resistance between Input and Output
CIN	Input capacitance per line



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Symbol	Test conditions	Min.	Тур.	Max.	Unit
Vbr	I _R = 1 mA	6	7	8	V
I _{RM}	V _{RM} = 3V			1	μΑ
Ri/o		80	100	120	Ω
R _d	$I_{pp} = 10 \text{ A}, t_p = 2.5 \ \mu s$ (see note 1)		1		Ω
Cin	at 0V bias		50		pF

Note 1 : to calculate the ESD residual voltage, please refer to the paragraph "ESD PROTECTION" on pages 4 & 5

TECHNICAL INFORMATION

FREQUENCY BEHAVIOR

The EMIF01-10005W5 is firstly designed as an EMI/RF1 $\,$ filter. This low-pass filter is characterized by the following parameters:

- Cut-off frequency
- Insertion loss
- High frequency rejection

Fig A1: EMIF01-10005W5 frequency response curve.



Figure A1 gives these parameters, in particular the signal rejection at the GSM frequency is about -24dB at 900MHz,

Fig A2: Measurement conditions



ESD PROTECTION

In addition to its filtering function, the EMIF01-10005W5 is particularly optimized to perform ESD protection.

ESD protection is based on the use of device which clamps at :

$$V_{CL} = V_{BR} + R_d.I_{PP}$$

This protection function is splitted in 2 stages. As shown in figure A3, the ESD strikes are clamped by the first stage S1 and then its remaining overvoltage is applied to the second stage through the resistor R. Such a configuration makes the output voltage very low at the Vout level.

Fig A3 : ESD clamping behavior



To have a good approximation of the remaining voltages at both Vin and Vout stages, we provide the typical dynamical resistance value Rd. By taking into account these following hypothesis : R>>Rd, R_G>>Rd and Rload>>Rd, it gives these formulas:

$$Vin = \frac{Rg.Vbr+Rd.Vg}{Rg}$$
$$Vout = \frac{R.Vbr+Rd.Vin}{R}$$

The results of the calculation done for V_G=8kV, R_G=330Ω (IEC1000-4-2 standard) and V_{BR}=7V (typ.) give:

<u>Vout = 7.3 V</u>

This confirms the very low remaining voltage across the device to be protected. It is also important to note that in this approximation the parasitic inductance effect was not taken into account. This could be few tenths of volts during few ns at the Vin side. This parasitic effect is not present at the Vout side due the low current involved after the resistance R.

Fig A4 : Measurement conditions



The measurements shown here after illustrate very clearly (Fig. A5a) the high efficiency of the ESD protection :

- no influence of the parasitic inductances on Vout stage
- Vout clamping voltage very close to $V_{\mbox{\scriptsize BR}}$



Fig A5 : Remaining voltage at both stages S1 (Vin) and S2 (Vout) during ESD surge

Please note that the EMIF01-10005W5 is not only acting for positive ESD surges but also for negative ones. For these kind of disturbances it clamps close to ground voltage as shown in Fig. A5b.

NOTE: DYNAMIC RESISTANCE MEASUREMENT

As the value of the dynamic resistance remains stable for a surge duration lower than $20\mu s$, the $2.5\mu s$ rectangular surge is well adapted. In addition both rise and fall times are optimized to avoid any parasitic phenomenon during the measurement of Rd.

Fig A6 : Rd measurement current wave



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CROSSTALK BEHAVIOR

1- Crosstalk phenomena

Fig A7 : Crosstalk phenomena



2- Digital Crosstalk

Fig A8 : Digital crosstalk measurement



Figure A8 shows the measurement circuit used to quantify the crosstalk effect in a classical digital application.

Figure A9 shows that in such a condition signal from 0 to 5V and rise time of 3 ns, the impact on the disturbed line is less than 100mV peak to peak. No data disturbance was noted on the concerned line. The same results were obtained with falling edges.





3- Analog Crosstalk





0	dB																	_		
0																				
-20	_											Ц			\downarrow		\parallel			
20											Ц				\downarrow	∦	11			
-40				Ц	Ц					\downarrow	Ц	Ц			4	Щ	Щ			
_				Ц							μ				4	\parallel	╢			
-60				Н	Ш				K	1	Ц	Щ		\square	4	Щ	Щ			
				\parallel	\parallel			_		+	\parallel	╢			+	\parallel	╢			
-80		~				1			Н	+	Н	╢		\square	+	Н	╢			
				\parallel	\parallel				\square	+	Н	╢		\square	+	╢	╢			
-100					Ш						Π	1				Ш	Ш]	_	
	1 10 100 1,000																			
	F(MHz)																			

Fig A11 : Typical analog crosstalk result

Figure A10 gives the measurement circuit for the analog application. In figure A11, the curve shows the effect of cell I/O1 on cell I/O2. In usual frequency range of analog signals (up to 100MHz) the effect on disturbed line is less than -43 dB.

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4 - PSpice model

Fig A12: PSpice model of one EMIF01 cell



Fig A13: PSpice parameters

	Dz	Df	Dr
BV	7	1000	1000
Cjo	25p	25p	1p
IBV	100u	100u	100u
IKF	1000	1000	1000
IS	10E-15	1.016E-15	10E-15
ISR	100p	100p	100p
Ν	1	1.0755	0.6
М	0.3333	0.3333	0.3333
RS	1	1	1m
VJ	0.6	0.6	0.6
TT	50n	50n	1n

of 27℃

Note This model is available for an ambient temperature





Fig A15: Comparison between PSpice simulation and measured frequency response



ORDER CODE



Order code	Marking	Package	Weight	Base qty	Delivery mode
EMIF01-10005W5	M12	SOT323-5L	5.4 mg	3000	Tape & reel

PACKAGE MECHANICAL DATA

SOT323-5L



		DIMEN	ISIONS	
REF.	Millim	neters	Inc	hes
	Min.	Max.	Min.	Max.
А	0.8	1.1	0.031	0.043
A1	0	0.1	0	0.004
A2	0.8	1	0.031	0.039
b	0.15	0.3	0.006	0.012
С	0.1	0.18	0.004	0.007
D	1.8	2.2	0.071	0.086
Е	1.15	1.35	0.045	0.053
е	0.65	Тур.		
Н	1.8	2.4	0.071	0.094
Q1	0.1	0.4	0.004	0.016

RECOMMENDED FOOTPRINT



Mechanical specifications									
Lead plating	Tin-lead								
Lead plating thickness	5μm min. 25 μm max.								
Lead material	Sn / Pb (70% to 90% Sn)								
Lead coplanarity	100µm max.								
Body material	Molded epoxy								
Flammability	UL94V-0								

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